

Patent

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Customer No.: 31561

Docket No.: 11843-US-PA

Application No.: 10/707,687

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Applicant : Chen et al.  
Application No. : 10/707,687  
Filed : 2004/1/5  
For : CHIP PACKAGE STRUCTURE AND PROCESS FOR  
FABRICATING THE SAME  
Art Unit : 2822  
Examiner : LEWIS, MONICA

TRANSMITTAL LETTER

002-1-571-273-8300

(Via fax : 1+13+7 pages)

Assistant Commissioner for Patents  
Alexandria, VA 22314

Dear Sir,

In response to the Office Action dated September 20, 2005, please find the relevant paper in response to paper No. 09142005 as follows:

- Amendment and Response to Office Action in (13) pages
- Replacement Sheet of Drawing in (7) pages

I believe that no fee is incurred. However, the Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No. 50-2620 (Order No.: 11843-US-PA).

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,  
JIANQ CHYUN Intellectual Property Office

Date :

Dec. 20, 2005

By :

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